



Sheet 1 of 1

Form 1449*	Atty. Docket No.: 303.572US1	Serial No. 09/253,611
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	Applicant: Paul A. Farrar	
	Filing Date: February 19, 1999	Group: 2812

U. S. PATENT DOCUMENTS

**Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
RP	4,273,859	06/16/1981	Mones, A., et al.	430	315	12/31/79
RP	4,789,648	12/06/1988	Chow, M., et al.	437	225	10/28/85

FOREIGN PATENT DOCUMENTS

**Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation Yes No
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OTHER DOCUMENTS

(Including Author, Title, Date, Pertinent Pages, Etc.)

**Examiner Initial	
RP	Bohr, M.T., "Interconnect Scaling - The Real Limiter to High Performance ULSI", <u>IEEE</u> , pp. 241-244, (1995)
RP	Davis, J., et al., "A Priori Wiring Estimations and Optimal Multilevel Wiring Networks for Portable ULSI Systems", <u>Electronic Components and Technology Conference</u> , pp. 1002-1008, (1996)
RP	Gwennap, L., "IC Makers Confront RC Limitations, IBM Leads Move to Copper Interconnects; TI Deploys Low-k Dielectric", <u>Microdesign Resources</u> , Microprocessor Report, pp. 14-18, (August 1997)
RP	Kaanta, C., et al., "Dual Damascene: A ULSI Wiring Technology", <u>VMIC Conference</u> , 144-152, (June 1991)
RP	Lakshminarayana, S., "Multilevel Dual Damascene Copper Interconnections", Rensselaer Polytechnic Institute, Ph.d Thesis, pp. 1-205, (1997)
RP	Licata, T., et al., "Dual Damascene AL Wiring for 256M DRAM", <u>VMIC Conference</u> , 596-602, (June 1995)
RP	Luther, B., et al., "Planar Copper-Polyimide Back end of the Line Interconnections for ULSI Devices", <u>1993 Proceedings 10th International VLSI Multilevel Interconnection Conference</u> , pp.15-21, (1993)
RP	Ryan, J.G., et al., "The evolution of interconnection technology at IBM", <u>IBM J. Res. Develop.</u> , 39(4), pp. 371-381, (1995)
RP	Singer, P., "New Interconnect Materials: Chasing the Promise of Faster Chips", <u>Semiconductor International</u> , pp. 52-56, (1994)
RP	Taur, Y., et al., "CMOS scaling into the 21st century 0.1 micrometer and beyond", <u>IBM J. Res. Develop.</u> , 39(1/2), pp. 245-260, (1995)
RP	Vollmer, B., et al., "Recent advances in the application of collimated sputtering", <u>Thin Solid Films</u> , 247, pp. 104-111, (1994)

Examiner <u>lm Pompey</u>	Date Considered <u>2-5-03</u>
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*Substitute Disclosure Statement Form (P10-1449)

**EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.